

All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (μm)
Body	BRASS	NPGR
Center contact	BRASS	NPGR
Outer contact		
Insulator	PTFE/LCP/PEEK	
Gasket		
Others parts	PTFE/LCP/PEEK	
-	-	-
-	-	-

Radiall 🏹 🕯		STRAI	GHT MALE RE	Technical Data Sheet ECEPTACLE FOR SMT SLIDE TYPE - REEL OF 400
PAGE 2/5 ISSUE 130	8C SERIES	SMP-MAX		PART NUMBER R222M00740
ELECTRICAL C	Standar 400	rd Cc	Unit Unit Inntact us	Other Contact us
npedance requency SWR 1.25* sertion loss F leakage oltage rating ielectric withstanding voltage sulation resistance	0-6 (+ 0.0000) 0.15* - - (NA - 335) 1000)	Ω GHz < F(GHz) Maxi √F(GHz) dB Ma F(GHz)) dB Ma Veff Maxi Veff Maxi Veff mini MΩ mini	axi Opera Herma	ENVIRONMENTAL ating temperature -55/+165 ℃ etic seal NA Atm.cm3/s I leakage NA
MECHANICAL C enter contact retention Axial force – Mating End Axial force – Opposite end Torque Recommended torque Mating Panel nut Mating life Weight	NA N.cr NA N.cr	7 N mini 7 N mini JA N.cm mini n	Assemb Others: *VSWR *Coaxia *Slide t Typical 0-3GHz Power >300W0 Radial	SPECIFICATION DITER CHARACTERISTICS by instruction: ************************************

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 Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of zone are clean. Placement of the receptacle on the mounting zone with an automatic machine of 'pi and place' type. A video camera is recommended for positioning of the component Adhesive agents must not be used on the receptacle. This process of soldering has been tested with convection oven .Below please find, the typical profile to use. The cleaning of printed circuit boards is not obliged . Verification of solder joints and position of the component by visual inspection. The remember the typical profile to use. The cleaning of printed circuit boards is not obliged . Verification of solder joints and position of the component by visual inspection. The remember the typical profile to use. The remember typical profile to use. The remember the typical profile to use. The remember typical profile to use. The cleaning of printed circuit boards is not obliged . The remember typical profile to use. The remember typical profile t	PAGE 3/5	ISSUE 1308C	SERIES SMP-MAX		PART NUM	MBER R222M00740
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$\frac{1}{260} + \frac{1}{260} + \frac{1}$						
$\frac{1}{260^{-0}} \frac{1}{10^{-0}} \frac{1}{10^{-0}}$						
$\frac{1}{200^{-1}} \int_{100^{-1}}^{100^{-1}} \int_{100^{-1}}^$		Area	Preheat Area	Reflow Area	Forced Cooling A	rea
$\frac{1}{200^{\circ}} \frac{1}{10^{\circ}} $		250			\	
$\frac{1}{1000} \int_{0}^{0} \int_{$					Max peak temperature: 260°C	
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0 60 120 180 240 300 Time (seconds) Time (seconds)						
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